

## TOKYO SEIMITSU CO., LTD.

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# **TOKYO SEIMITSU announces first shipment** **“AD20T”, world’s most compact** **Twin Spindle Semi Automatic Wafer Dicing Machine**

TOKYO SEIMITSU CO., LTD. (Kazuo Fujimori, President & CEO) commenced shipment\*1 of the new “AD20T”, the world’s smallest Twin Spindle Semi Automatic Wafer Dicing Machine\*2. The AD20T now enables up to 2x throughput and achieving a reduction of 40% of the footprint compared to existing machines for processing of electronic devices such as LED, small semiconductor chips such as Discrete, and PKG devices such as QFN/BGA.

### <Background>

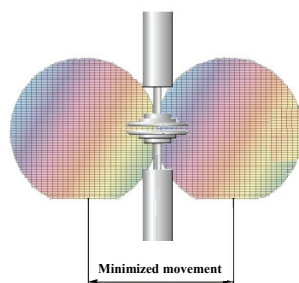
It is standard industry best practice to employ semi automatic dicing machines to reduce the costs incurred in the early stages of component manufacturing of electronic devices such as LED, small semiconductor chips such as Discrete, and PKG devices such as QFN/BGA. Recent effects from the dramatic drop in spot pricing for such components has lead to even further pressure on manufacturers to adopt Semi Automatic dicing machines achieving better ROI(Return of Investment) through lower Cost of Ownership by minimized processing time and efficient Clean Room use.

TOKYO SEIMITSU has responded conscientiously to customer needs, by developing the “AD20T”, which offers significantly increased throughput within a remarkably space saving machine. The “AD20T”, which has already commenced sales and shipping, boasts the world’s smallest footprint by employing TOKYO SEIMITSU’s ground breaking Opposing Twin Spindle technology\*3, thereby allowing significant increases in clean room efficiency as well as improved processing performance.

### <Main Features of “AD20T”>

#### 1. High Throughput

“AD20T” enables up to 2x faster throughput than single spindle Dicing Machines by use of two spindles, which enables serial dicing.



## 2. World's smallest footprint

The Core Technologies holding by TOKYO SEIMITSU has created the break through state-of-the-art layout (PAT.P), minimizing open spaces and achieving a reduction of 40% of the footprint compared to existing machines.

## 3. Wide Capability for Dicing Processes

“AD20T” accommodates cutting work size for materials up to 200mm circular, or 250mm rectangular despite the remarkable reduction in machine footprint size. The new spindle operation and machine balance optimization maintains industry-leading dicing performance.

While the wide materials processing capability is a significant feature of “AD20T” each Spindle can adopt individual blades to enhance precision cutting performance using the step-cut mode. Hence “AD20T” has an enormous range of processing options to meet the most specialized customer requirements.

## 4. User-friendly operation

“AD20T” bundles fully renewed GUI (Graphical User Interface) and 17 inch LCD touch panel to allow easy user operation. Status for each operating module, including Processing and Tool Conditions, can be interactively displayed on screen. Touch screen operation also adds to the remarkable ease of usage.



Note)

\*1 As of October 2009, multiple orders have been received.

\*2 Test-Cut commenced in May 2009, Sales efforts began from August 2009.

\*3 Opposing Twin Spindle was a world first technology first invented and deployed in dicing machines by TOKYO SEIMITSU since 1999